

# OM SENI

## MBRA340T3G Surface Mount Schottky Power Rectifier

### SMA Power Surface Mount Package

Employing the Schottky Barrier principle in a large area metal-to-silicon power diode. State of the art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity diodes in surface mount applications where compact size and weight are critical to the system.

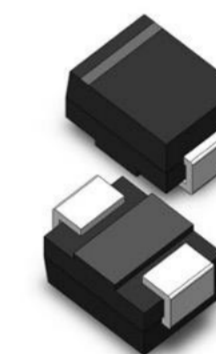
#### Features

- Small Compact Surface Mountable Package with J-Bent Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Very Low Forward Voltage Drop
- Guardring for Stress Protection
- These Devices are Pb-Free and are RoHS Compliant\*

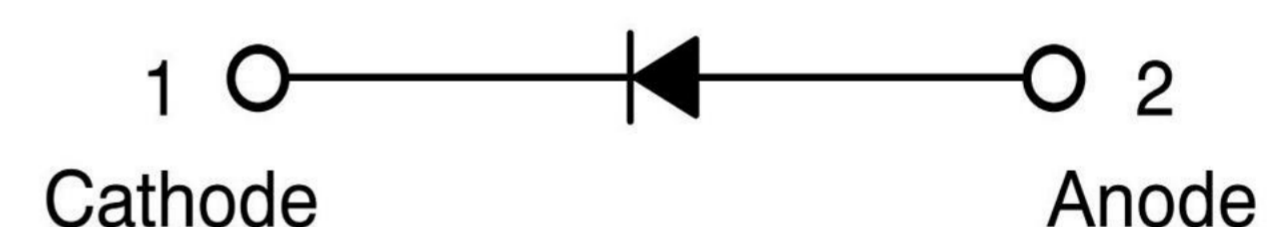
#### Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 70 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Cathode Lead Indicated by Polarity Band
- ESD Ratings:
  - ◆ Machine Model = C
  - ◆ Human Body Model = 3B
- Device Meets MSL 1 Requirements

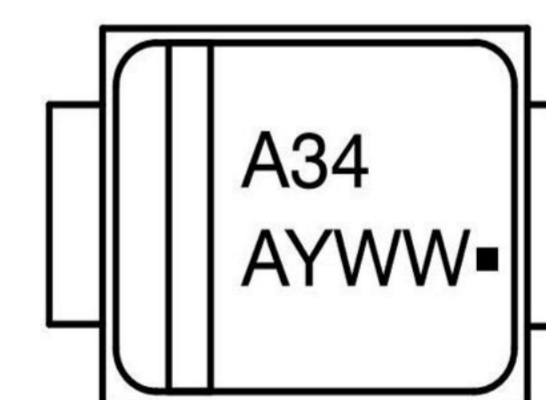
### SCHOTTKY BARRIER RECTIFIER 3.0 AMPERES 40 VOLTS



SMA  
CASE 403D  
STYLE 1



#### MARKING DIAGRAM



- A34 = Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
▪ = Pb-Free Package

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MBRA340T3G	SMA (Pb-Free)	5,000 / Tape & Reel **

\*\* 12 mm Tape, 13" Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	40	V
Average Rectified Forward Current (At Rated $V_R$ , $T_L = 100^\circ\text{C}$ )	$I_O$	3.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	100	A
Storage/Operating Case Temperature	$T_{stg}, T_C$	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature (Note 1)	$T_J$	-55 to +150	$^\circ\text{C}$
Voltage Rate of Change (Rated $V_R$ , $T_J = 25^\circ\text{C}$ )	dv/dt	10,000	V/ $\mu\text{s}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance – Junction-to-Lead (Note 2)	$R_{\theta JL}$	15	$^\circ\text{C}/\text{W}$
Thermal Resistance – Junction-to-Ambient (Note 2)	$R_{\theta JA}$	81	$^\circ\text{C}/\text{W}$

- Mounted on 2" Square PC Board with 1" Square Total Pad Size, PC Board FR4.

## ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value		Unit
		$T_J = 25^\circ\text{C}$	$T_J = 100^\circ\text{C}$	
Maximum Instantaneous Forward Voltage (Note 3) ( $I_F = 3.0\text{ A}$ )	$V_F$	0.450	0.390	Volts
Maximum Instantaneous Reverse Current ( $V_R = 40\text{ V}$ )	$I_R$	0.3	15	mA

- Pulse Test: Pulse Width  $\leq 250\ \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

## TYPICAL CHARACTERISTICS

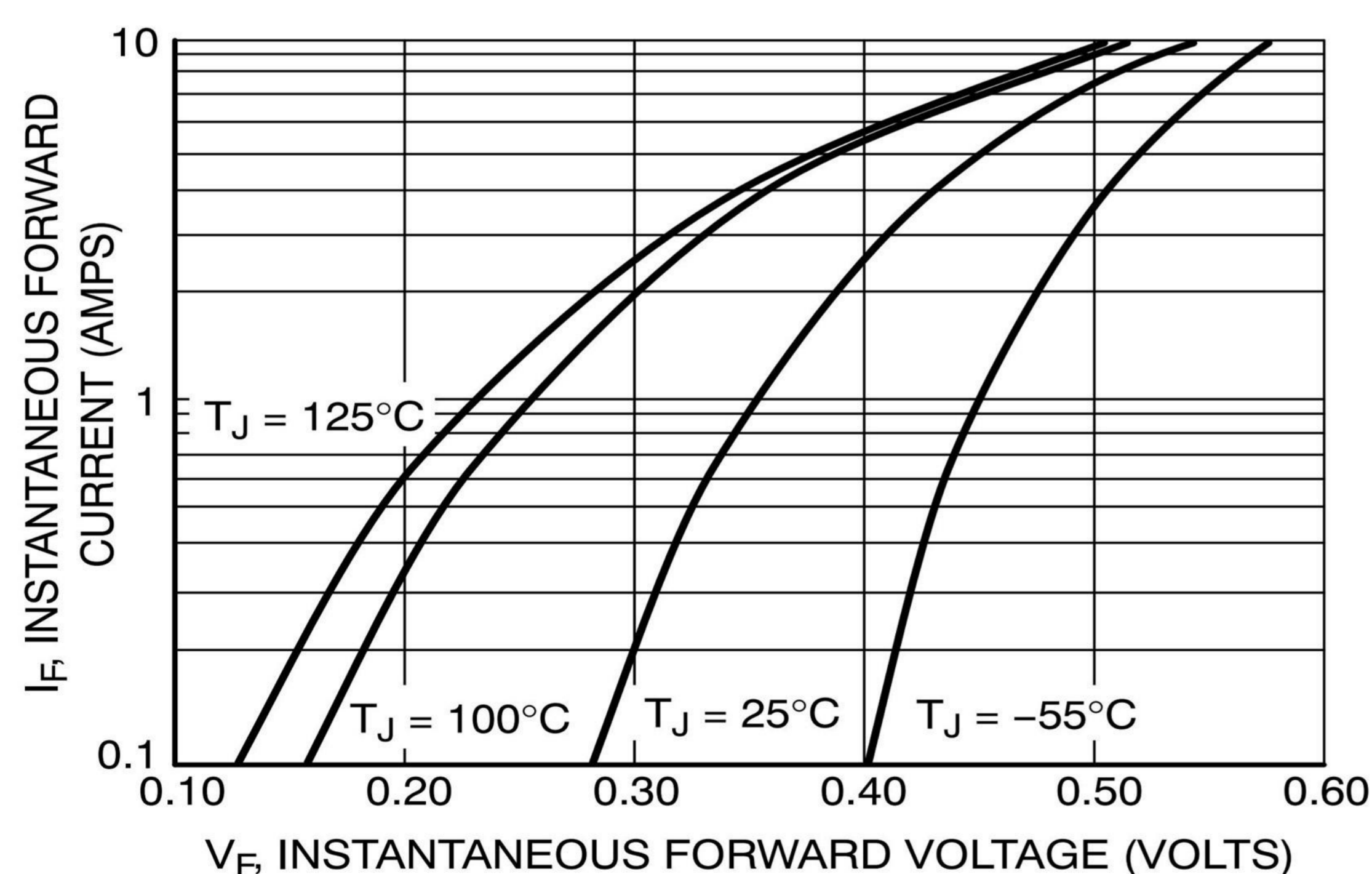


Figure 1. Typical Forward Voltage

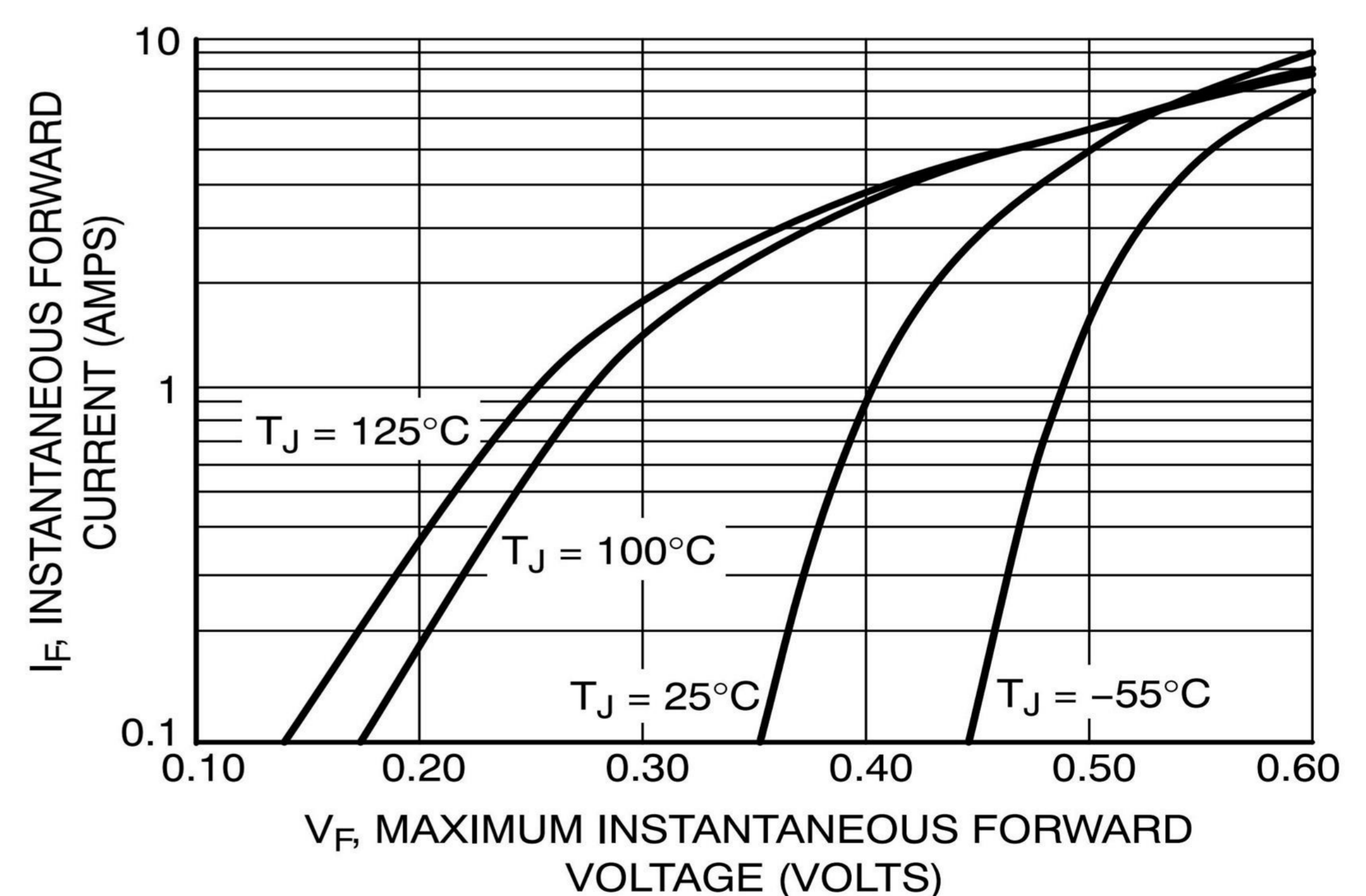


Figure 2. Maximum Forward Voltage

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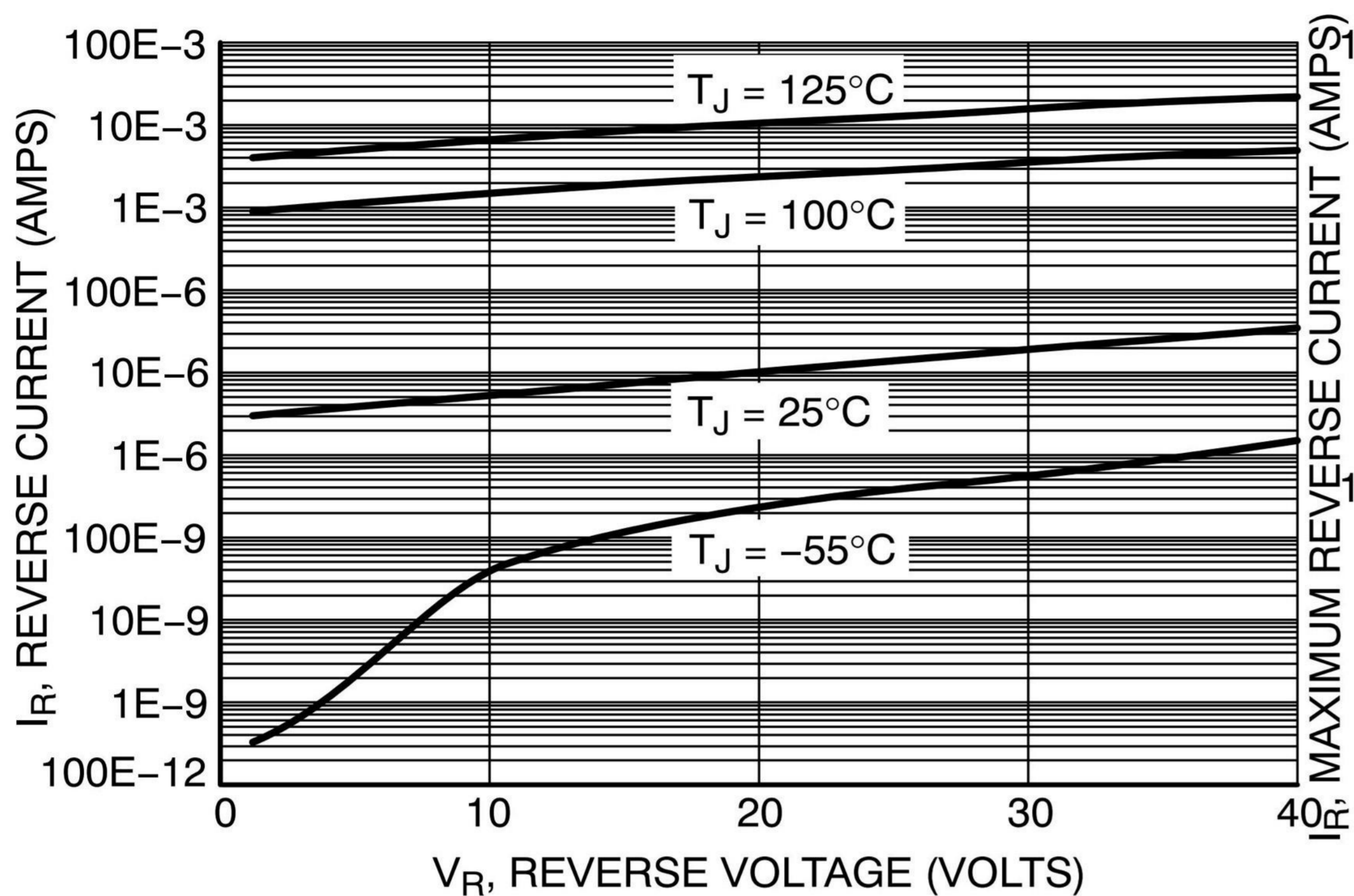


Figure 3. Typical Reverse Current

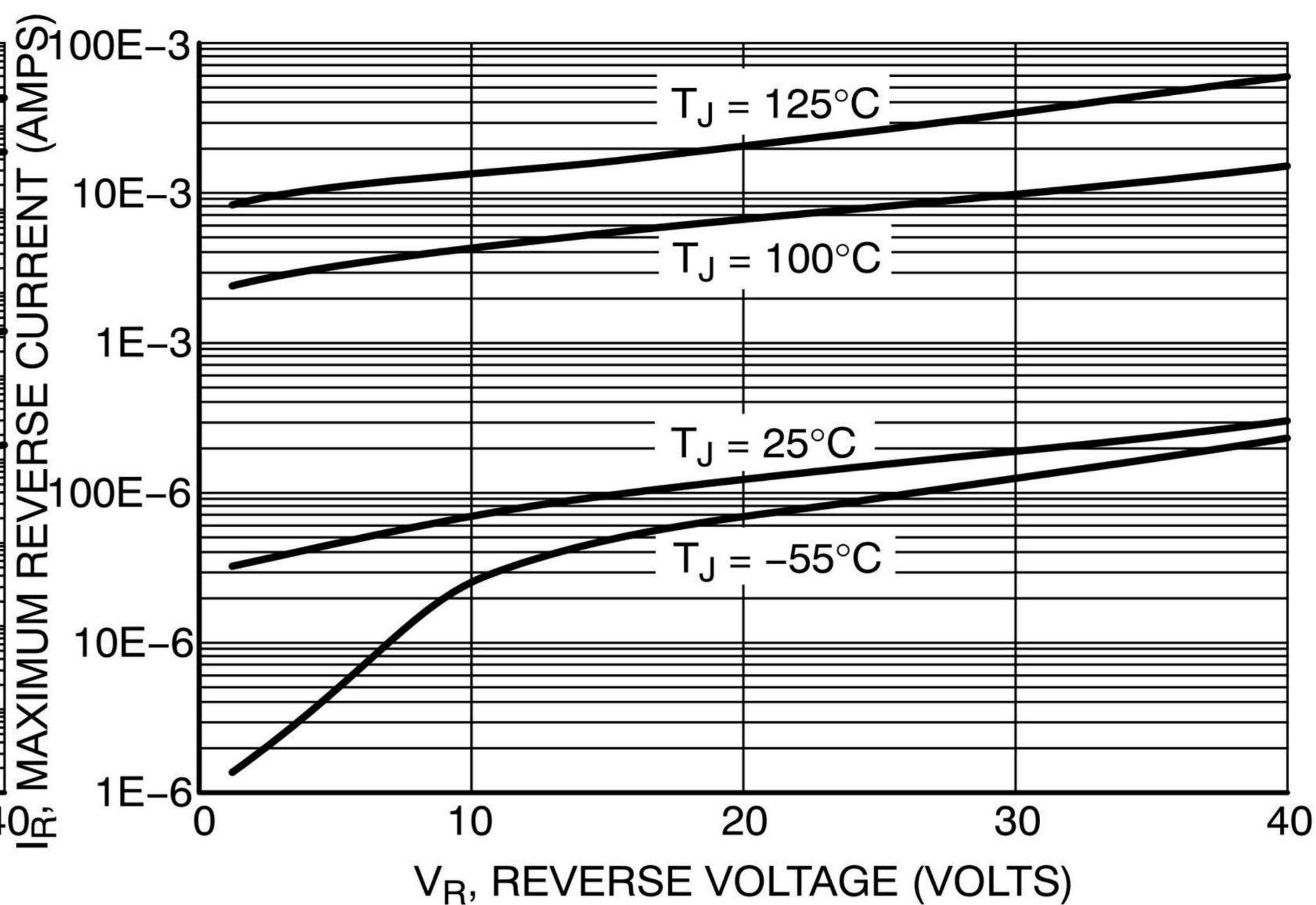


Figure 4. Maximum Reverse Current

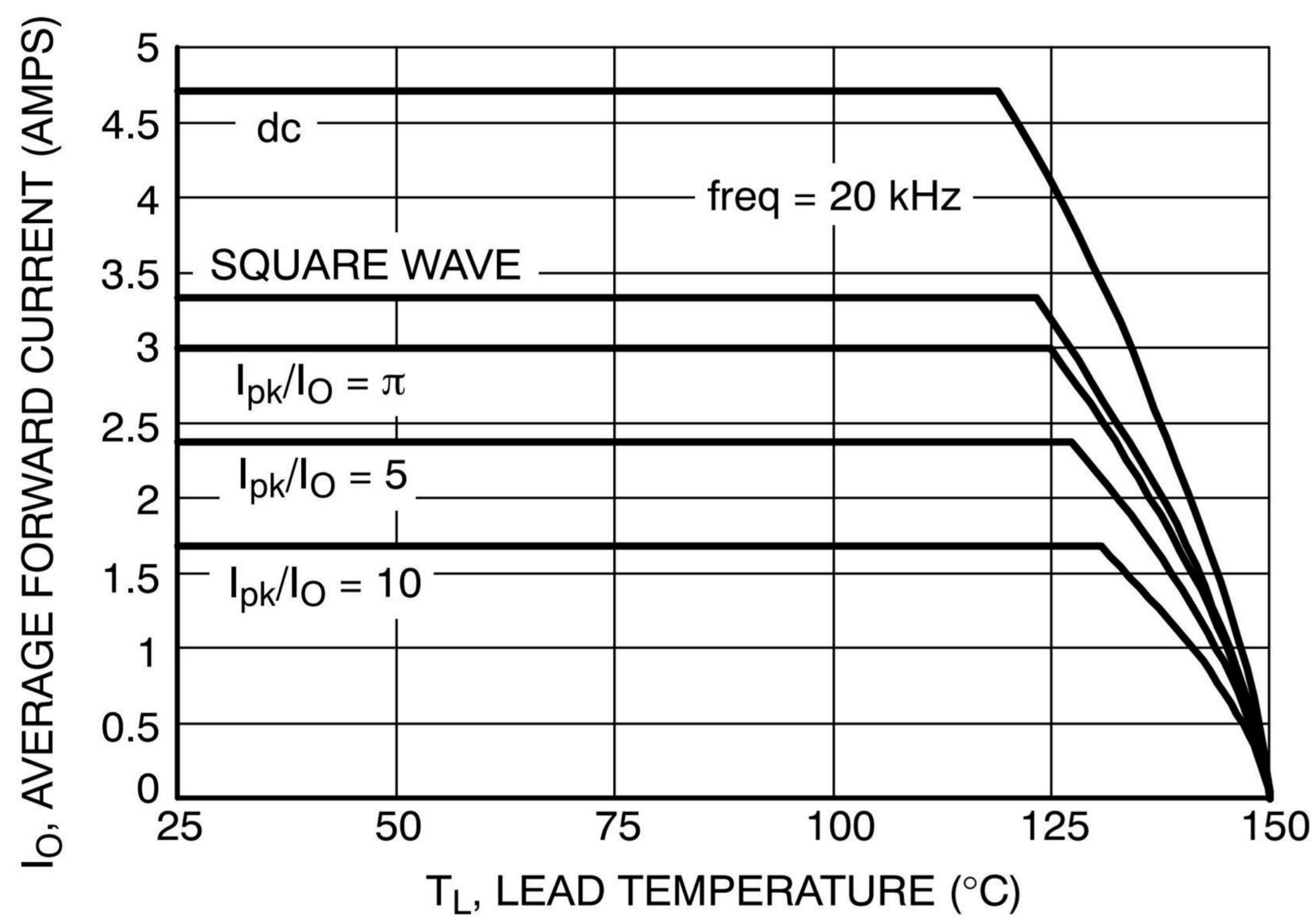


Figure 5. Current Derating

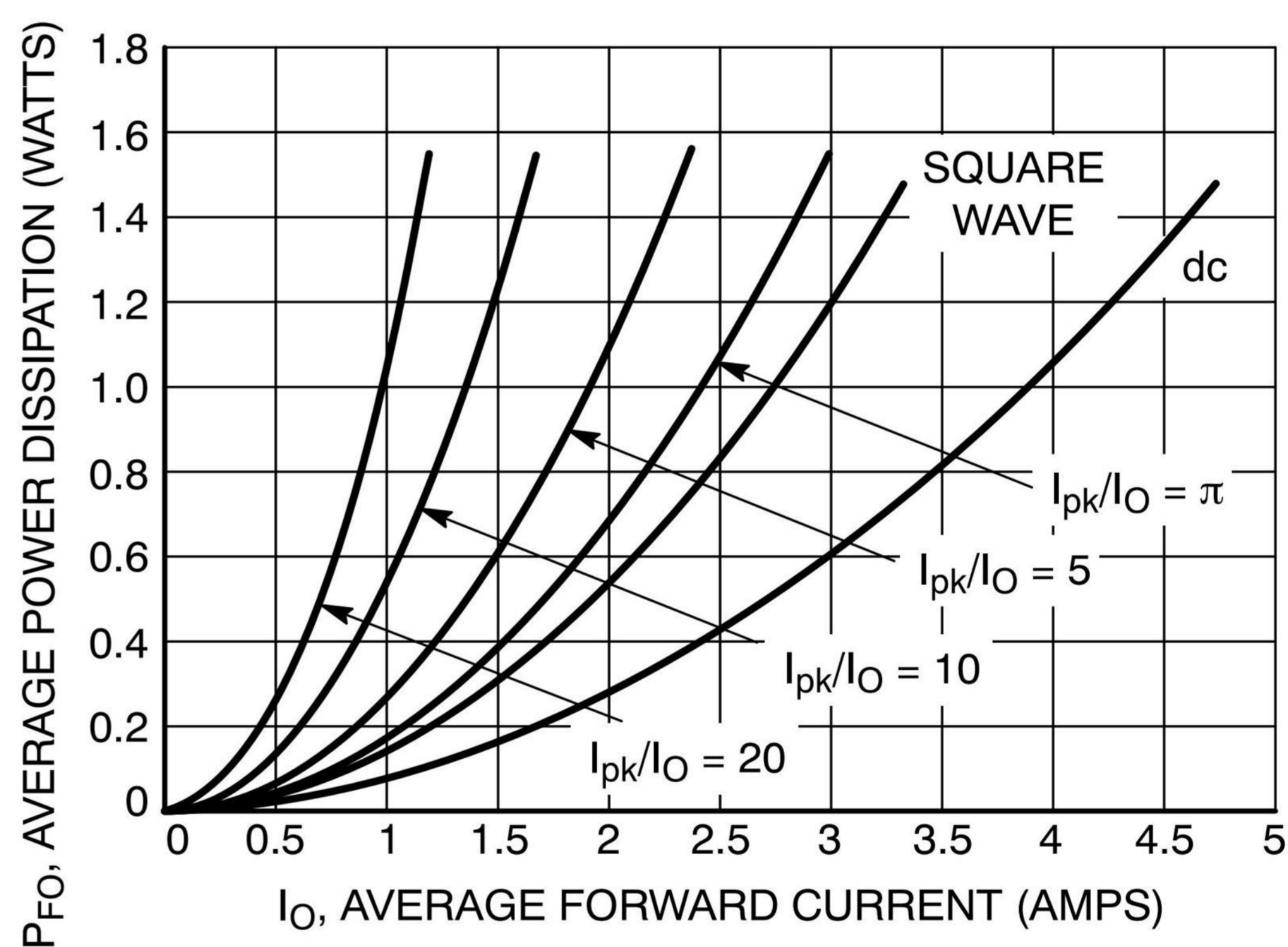


Figure 6. Forward Power Dissipation

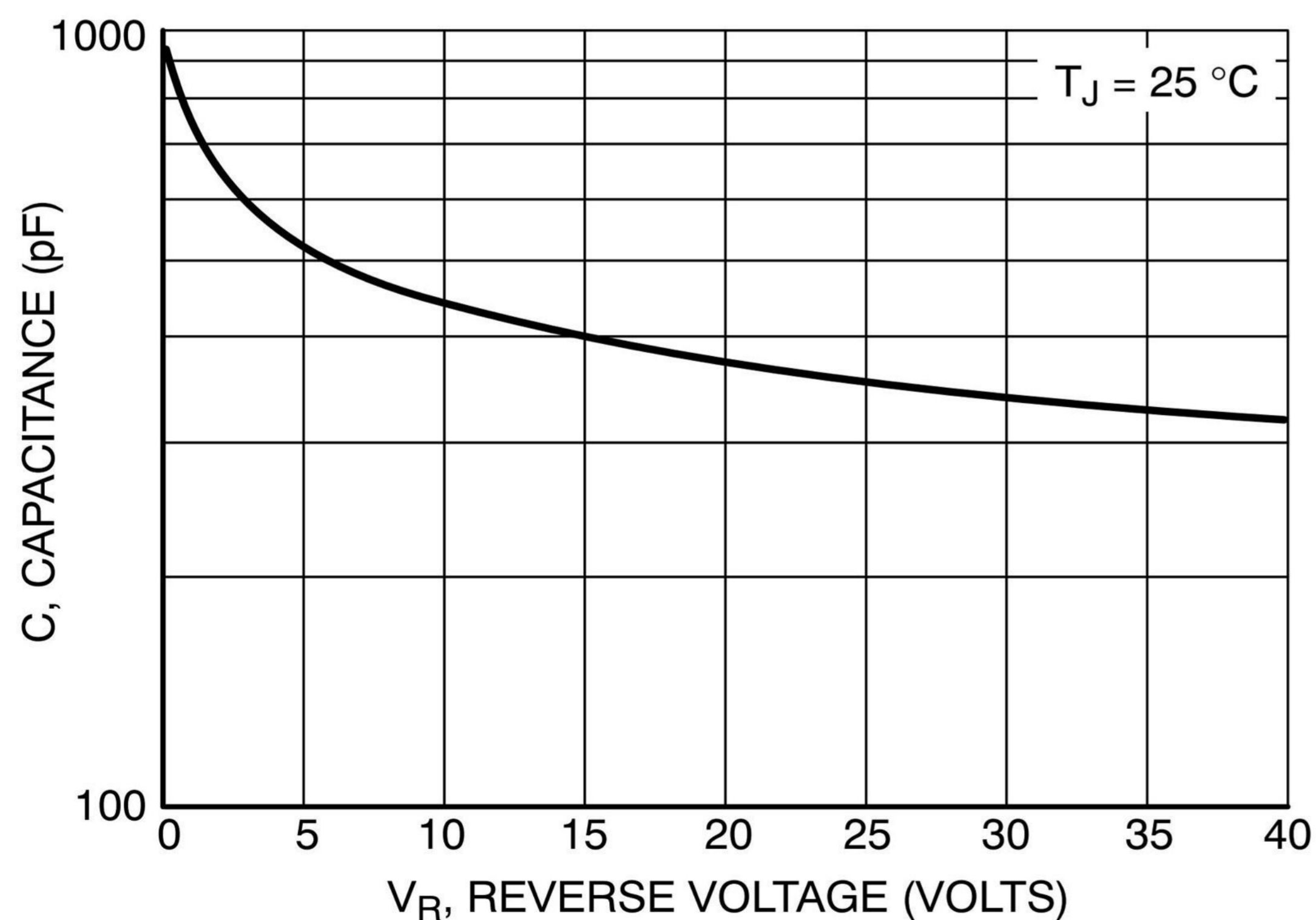


Figure 7. Capacitance

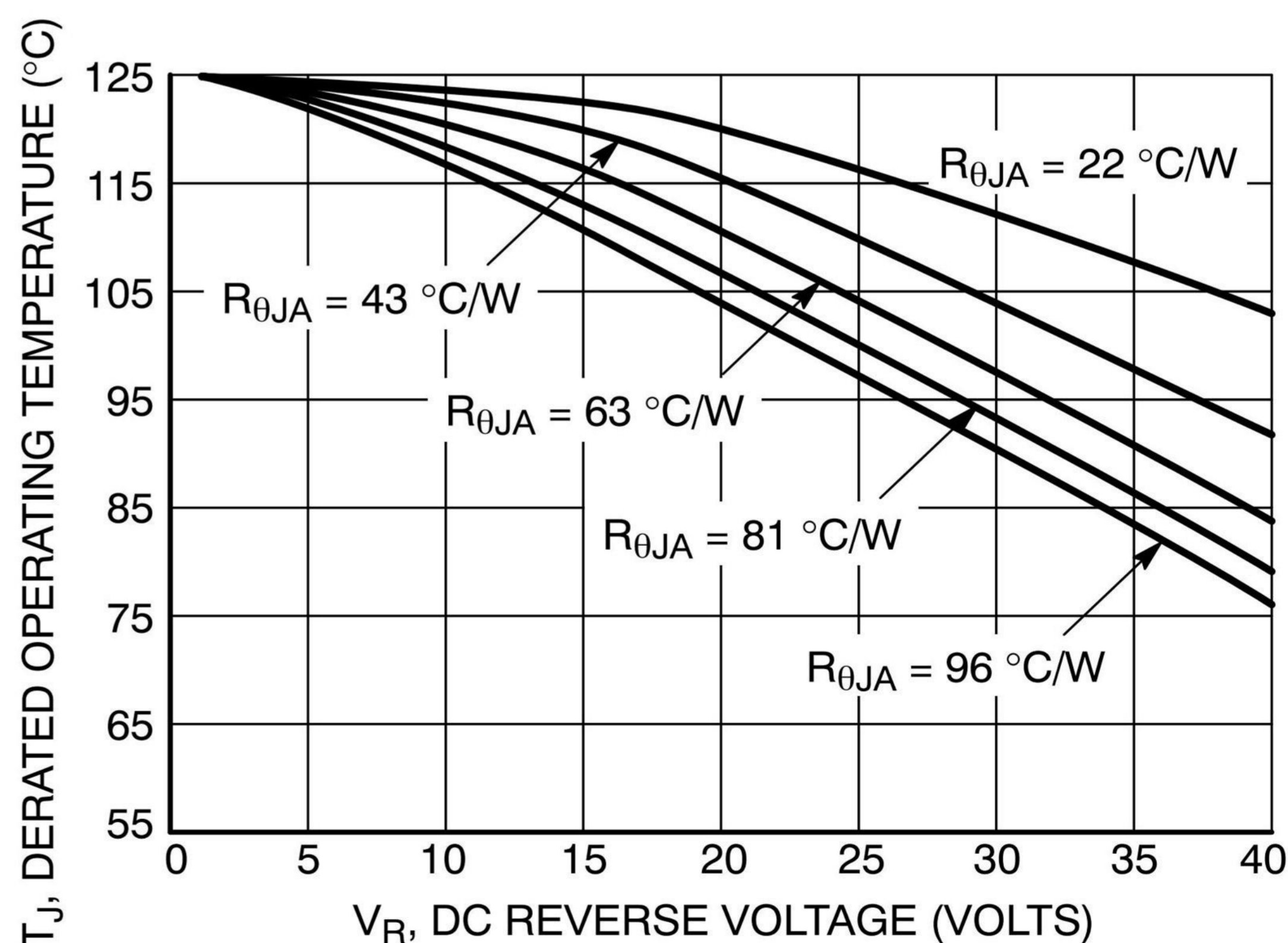


Figure 8. Typical Operating Temperature Derating

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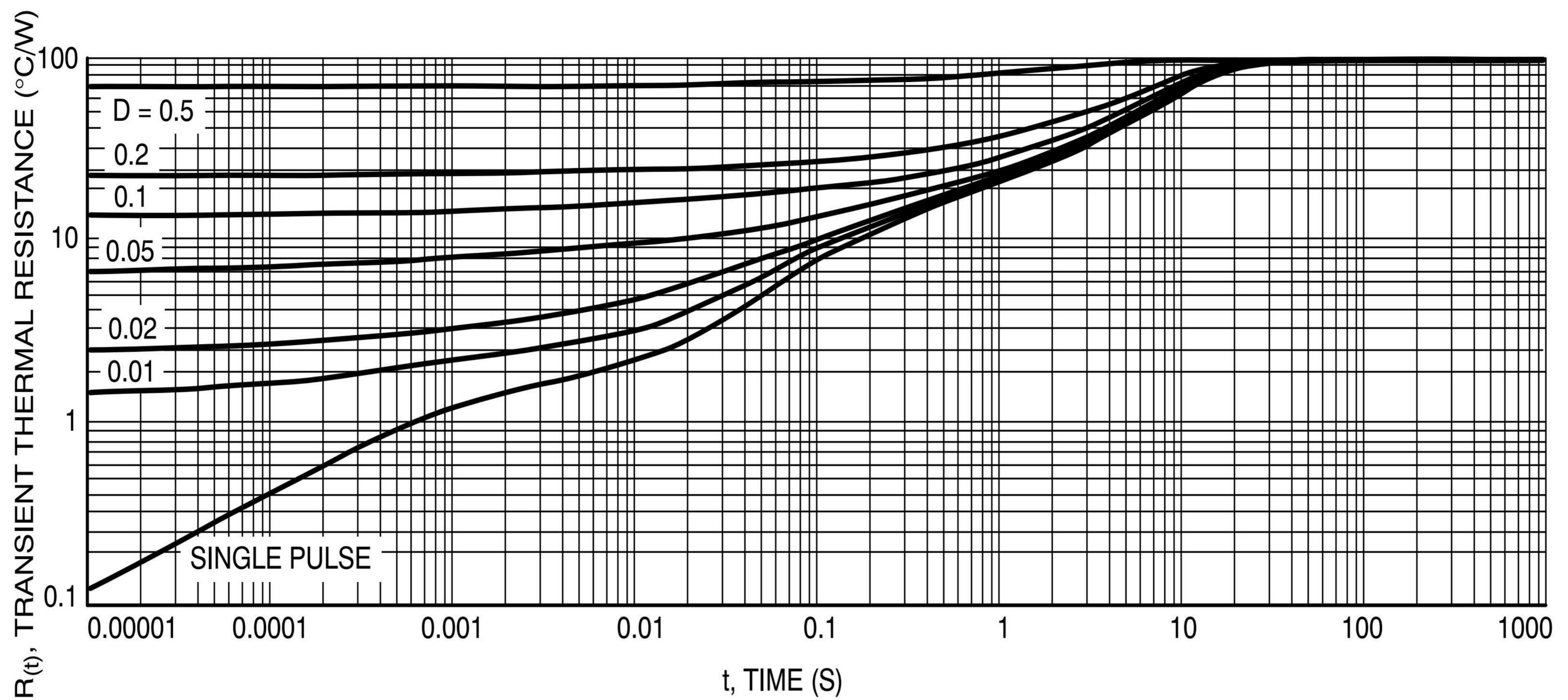


Figure 9. Thermal Response, Junction-to-Ambient (min pad)

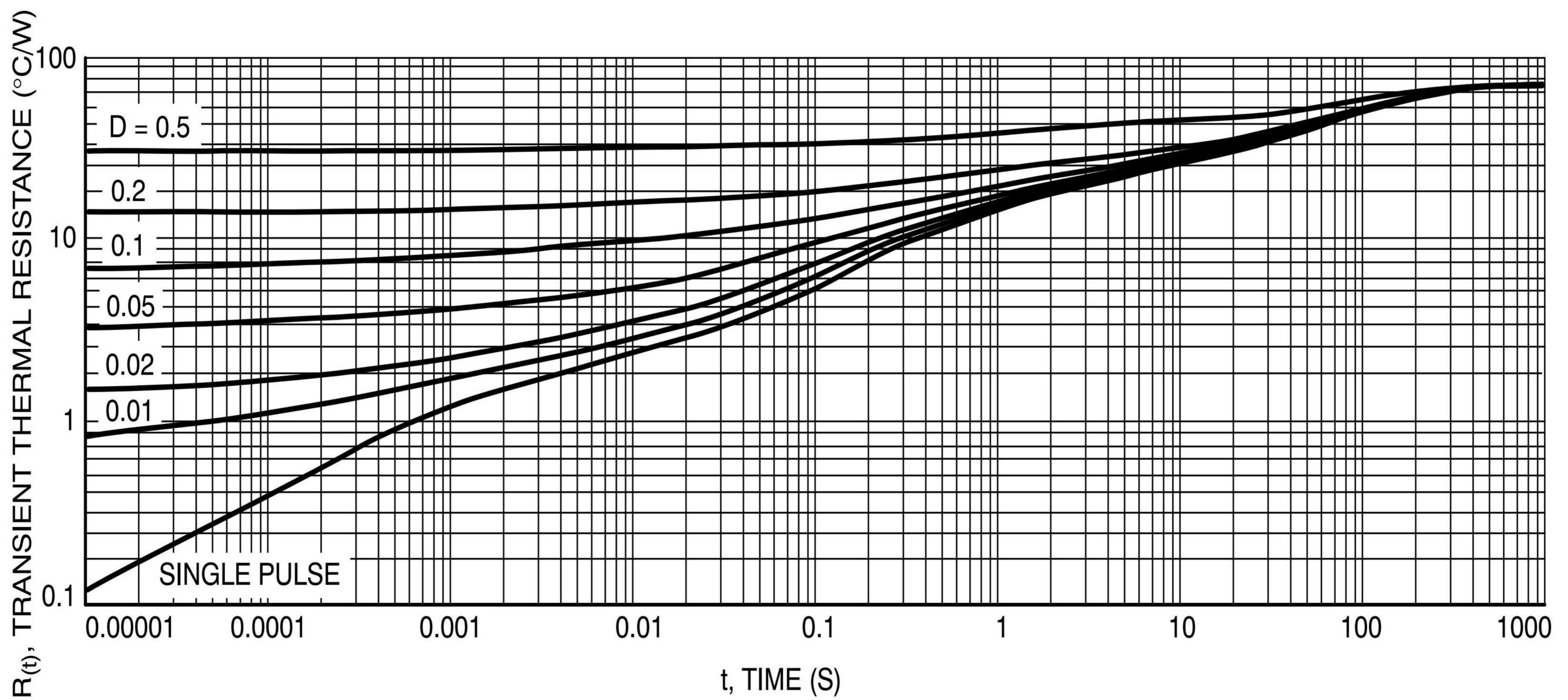


Figure 10. Thermal Response, Junction to Ambient (1 inch pad)

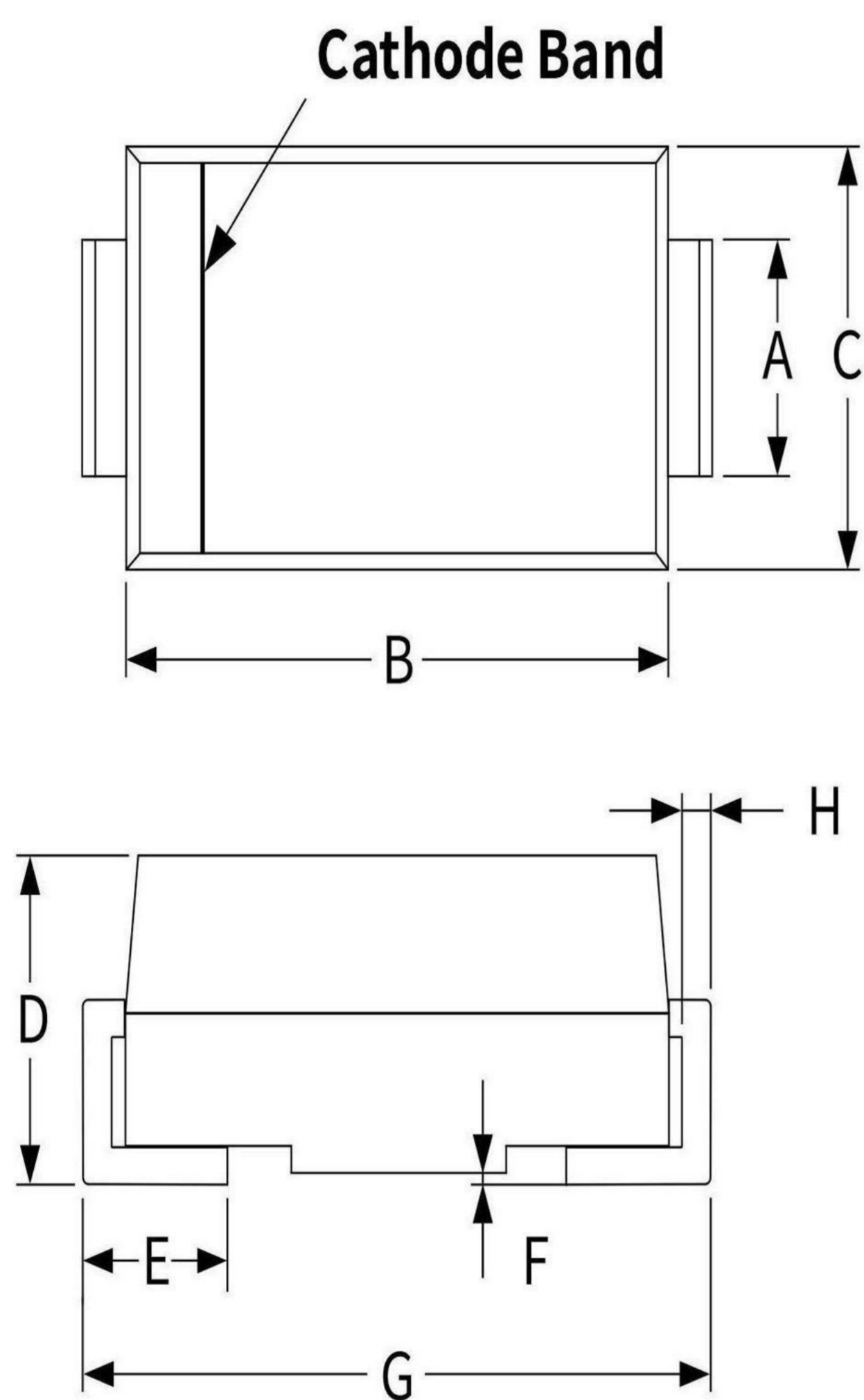
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## Ordering Information

PACKAGE	PACKAGE CODE	UNIT WEIGHT(g)	REEL(pcs)	BOX(pcs)	CARTON(pcs)	DELIVERY MODE
SMA	R2	0.07	5000	10000	80000	13"

## Package Outline Dimensions (SMA/DO-214AC)

Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.25	1.65	0.049	0.065
B	3.95	4.65	0.156	0.183
C	2.35	2.85	0.093	0.112
D	1.98	2.41	0.078	0.095
E	0.76	1.52	0.030	0.060
F	-	0.203	-	0.008
G	4.70	5.30	0.185	0.209
H	0.15	0.31	0.006	0.012



## Suggested Pad Layout

Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
M	1.70	-	0.067	-
J	2.10	-	0.082	-
K	-	2.30	-	0.090

